

Title (en)
DIE ASSEMBLY AND LOCATING METHOD

Title (de)
STEMPELANORDNUNG UND ORTUNGSVERFAHREN

Title (fr)
ENSEMBLE DE MATRICE ET PROCÉDÉ DE LOCALISATION

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EP 3272534 A1 20180124 (EN)

Application
EP 17182687 A 20170721

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Abstract (en)
The invention provides a reusable assembly adapted for use in one or more of foiling, embossing and debossing. The assembly comprises a chase (104), having a first surface (114) with a plurality of user identifiable discrete grid positions (116) arranged within a grid and adapted for connection to a press. It further comprises a die assembly comprising a die (110) defining a first surface for foiling, embossing or debossing and connected to a linkage (106) defining a second surface (134) adapted for separable engagement with the first surface of the chase at various grid positions. A method of repositioning a die is also provided.

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Citation (search report)

- [X] WO 0187602 A2 20011122 - SIL DIE SYSTEMS LTD [GB], et al
- [A] GB 2510809 A 20140820 - SIL DIE SYSTEMS LTD [GB]
- [A] US 6341557 B1 20020129 - HUTCHISON GLENN E [US], et al

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